H273-Z80 (rev. AAW1) | (rev.AAN1)

High Density Server – AMD EPYC™ 9004 DP 2U 4-Node Server 24 x Gen4 NVMe/SATA 3000W | Application: HCI & Hybrid/Private Cloud Server

- 2U 4-node rear access server system
- AMD EPYC™ 9004 series processor family
- Dual processor per node, 5nm technology
- 12-Channel RDIMM DDR5 per processor, 96 x DIMMs
- Dual ROM Architecture supported
- 8 x 1Gb/s LAN ports (Intel® I350-AM2)
- 4 x Dedicated management ports
- 24 x 2.5" Gen4 NVMe/SATA hot-swappable bays
- 4 x M.2 slots with PCIe Gen4 x4 interface **(optional)**
- 8 x LP PCIe Gen5 x16 slots
- 4 x OCP 3.0 Gen5 x16 mezzanine slots
- Dual 3000W (240V) 80 PLUS Titanium redundant power supply

Request a Quote

Compare

OVERVIEW SPECIFICATIONS SUPPORT RESOURCES BUY

Dimensions (WxHxD, mm)

2U 4-Node - Rear access
440 x 87.5 x 877

Motherboard

MZ83-HD0

CPU

AMD EPYC™ 9004 series processor family
Dual processor, 5nm technology
Up to 96-core, 192 threads per processor
Supports CPU 240W at ambient 30°C

Socket

Per Node:
2 x LGA 6096

Total:
8 x LGA 6096

Socket SP5

Chipset

System on Chip

Memory

Per node:
24 x DIMM slots

Total:
96 x DIMM slots
DDR5 memory supported only
12-Channel memory architecture
RDIMM modules up to 128GB supported
3DS RDIMM modules up to 256GB supported
Memory speed: Up to 4800 MHz

LAN

Per node:
2 x 1GbE LAN ports (1 x Intel® I350-AM2)
Support NCSI function
1 x Dedicated management port

Total:
8 x 1GbE LAN ports (4 x Intel® I350-AM2)
Support NCSI function
4 x Dedicated management ports

Video

Integrated in Aspeed® AST2600
2D Video Graphic Adapter with PCIe bus interface
1920x1200@60Hz 32bpp, DDR4 SDRAM

Management chip on CMC board:
Integrated in Aspeed® AST2520A2-GP

Storage

Per node:
6 x 2.5" Gen4 NVMe/SATA/SAS hot-swappable bays

Total:
24 x 2.5" Gen4 NVMe/SATA/SAS hot-swappable bays

SAS card is required for SAS devices support

SAS

Supported via add-on SAS Card

RAID

N/A

Expansion Slots

Per node:
Riser Card CRSH01Q:
- 1 x PCIe x16 (Gen5 x16) low-profile slot, from CPU_0

Riser Card CRSH01R:
- 1 x PCIe x16 (Gen5 x16) low-profile slot, from CPU_0

1 x OCP 3.0 mezzanine slot with PCIe Gen5 x16 bandwidth, from CPU_0
Supports NCSI function

*1 x M.2 slot:
- M-key
- PCIe Gen4 x4, from CPU_0
- Supports NGFF-2280/22110 cards

Total:
Riser Card CRSH01Q x 4:
- 4 x PCIe x16 (Gen5 x16) low-profile slots, from CPU_0

Riser Card CRSH01R x 4:
- 4 x PCIe x16 (Gen5 x16) low-profile slots, from CPU_0

4 x OCP 3.0 mezzanine slots with PCIe Gen5 x16 bandwidth, from CPU_0
Support NCSI function

*4 x M.2 slots:
- M-key
- PCIe Gen4 x4, from CPU_0
- Support NGFF-2280/22110 cards

***Optional kit for M.2 extension riser card**
PN: 9CMTP192NR-00

Internal I/O

Per node:
1 x TPM header

Front I/O

Per node:
1 x Power button with LED
1 x ID button with LED
1 x Status LED
1 x System reset button

Total:
4 x Power buttons with LED
4 x ID buttons with LED
4 x Status LEDs
4 x System reset buttons
*1 x CMC status LED
*1 x CMC reset button

***Only one CMC status LED and reset button per system**

Rear I/O

Per node:
2 x USB 3.2 Gen1
1 x Mini-DP
2 x RJ45
1 x RJ45 MLAN
1 x Node Status LED

Total:
8 x USB 3.2 Gen1
4 x Mini-DP
8 x RJ45
4 x RJ45 MLAN
4 x Node Status LEDs

***Spanning Tree Protocol (STP) must be enabled in LAN switch function if using ring topology**

Backplane I/O

Backplane P/N: 9CBPH7O1NR-00
PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s

TPM

1 x TPM header with SPI interface
Optional TPM2.0 kit: CTM010

Power Supply

Dual 3000W (240V) 80 PLUS Titanium redundant power supply

AC Input:
- 100-127V~/ 16A, 50-60Hz
- 200-240V~/ 16A, 50-60Hz

DC Input:
- 240Vdc/ 16A

DC Output:
- Max 1200W/ 100-127V~
+ 12.2V/ 98.36A
+ 12.2Vsb/ 3A
- Max 2600W/ 200-207V~
+ 12.2V/ 213A
+ 12.2Vsb/ 3A
- Max 3000W/ 208-240V~
+ 12.2V/ 245.9A
+ 12.2Vsb/ 3A

NOTE: The system power supply requires C19 power cord

System Management

Aspeed® AST2600 management controller
GIGABYTE Management Console (AMI MegaRAC SP-X) web interface

Dashboard
HTML5 KVM
Sensor Monitor (Voltage, RPM, Temperature, CPU Status ...etc.)
Sensor Reading History Data
FRU Information
SEL Log in Linear Storage / Circular Storage Policy
Hardware Inventory
Fan Profile
System Firewall
Power Consumption
Power Control
LDAP / AD / RADIUS Support
Backup & Restore Configuration
Remote BIOS/BMC/CPLD Update
Event Log Filter
User Management
Media Redirection Settings
PAM Order Settings
SSL Settings
SMTP Settings

OS Compatibility

Please refer to OS compatibility table in support page

System Fans

4 x 80x80x80mm (16,500rpm)

Operating Properties

Operating temperature: 10°C to 35°C
Operating humidity: 8-80% (non-condensing)
Non-operating temperature: -40°C to 60°C
Non-operating humidity: 20%-95% (non-condensing)

Packaging Dimensions

1179 x 700 x 380 mm

Packaging Content

1 x H273-Z80
8 x CPU heatsinks
1 x Rail Kit

Part Numbers

- Barebone package: 6NH273Z80DR000AAW1*
- Motherboard: 9MZ83HD0UR-000
- Rail kit: 25HB2-A66125-K0R
- CPU heatsink: 25ST1-25320N-M1R/25ST1-25320Q-M1R
- M.2 extension riser card: 9CMTP192NR-00 **(optional)**
- Backplane board: 9CBPH7O1NR-00
- Fan module: 25ST2-888020-S1R
- Riser card - CRSH01Q: 9CRSH01QNR-00
- Riser card - CRSH01R: 9CRSH01RNR-00
- Rear IO board (incl. LAN chip): 9CLBH160NR-00
- Mini-DP to D-Sub cable: 25CRN-200801-K1R
- Power Supply: 25EP0-230009-L0S
- C19 power cord 125V/15A (US): 25CP1-018000-Q0R **(optional)**
- C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R **(optional)**

* The entire materials provided herein are for reference only. GIGABYTE reserves the right to modify or revise the content at anytime without prior notice.
* Advertised performance is based on maximum theoretical interface values from respective Chipset vendors or organization who defined the interface specification. Actual performance may vary by system configuration.
* All trademarks and logos are the properties of their respective holders.
* Due to standard PC architecture, a certain amount of memory is reserved for system usage and therefore the actual memory size is less than the stated amount.